



PK168 (v1.4) December 12, 2018

# 100% Material Declaration Data Sheet for TQ100 Package

Average Weight : 0.6590 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight ( in grams)	Component % of total
Silver Epoxy					<b>0.001356</b>	<b>0.20577%</b>
	Silver	7440-22-4	85.3		0.001157	
	Epoxy resin	Trade Secret	5.4		0.000073	
	Organic anhydride	Trade Secret	3.1		0.000042	
	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl) phenol; 4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2, 6-bis (2,3-epoxypropyl) phenoxy)-2-hydroxypropyl	-	3.1		0.000042	
	Anhydride	Trade Secret	3.1		0.000042	
Die					<b>0.009464</b>	<b>1.43612%</b>
	Silicon	7440-21-3	100.00		0.009464	
Gold Wire					<b>0.001332</b>	<b>0.20212%</b>
	Gold	7440-57-5	99.0475		0.001319	
	Palladium	7440-05-3	0.95		0.000013	
	Calcium	7440-70-2	0.002		0.000000	
	Beryllium	7440-41-7	0.0005		0.000000	
Mold Compound					<b>0.539785</b>	<b>81.90971%</b>
	Epoxy Resin	Trade Secret	7.5		0.040484	
	Phenol Resin	Trade Secret	7.5		0.040484	
	Silica(Amorphous) A	60676-86-0	81.45		0.439655	
	Silica(Amorphous) B	7631-86-9	3		0.016194	
	Carbon Black	1333-86-4	0.55		0.002969	
Leadframe					<b>0.107063</b>	<b>16.24628%</b>
	Nickel Plating	7440-02-0	0.325		0.000348	
	Palladium Plating	7440-05-3	0.0175		0.000019	
	Gold Plating	7440-57-5	0.004		0.000004	
	Copper	7440-50-8	95.5535		0.102302	
	Magnesium	7439-95-4	0.175		0.000187	
	Silicon	7440-21-3	0.725		0.000776	
	Nickel	7440-02-0	3.2		0.003426	

## Revision History

Date	Version	Description of Revisions
3/16/2006	1.0	Initial Xilinx release.
7/5/2006	1.1	100% Material Declaration
9/29/2006	1.2	Updated component descriptions.
1/24/2013	1.3	Updated component weight
12/12/2018	1.4	Updated Leadframe component, per XCN18024

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